HEXFRED®
Ultrafast Soft Recovery Diode, 120 A

SOT-227

FEATURES

- Fast recovery time characteristic
- Electrically isolated base plate
- Large creepage distance between terminal
- Simplified mechanical designs, rapid assembly
- UL approved file E78996
- Compliant to RoHS directive 2002/95/EC
- Designed and qualified for industrial level

Pb-free
RoHS COMPLIANT

DESCRIPTION/APPLICATIONS

The dual diode series configuration (HFA120FA120P) is used for output rectification or freewheeling/clamping operation and high voltage application.
The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built.
These modules are intended for general applications such as HV power supplies, electronic welders, motor control and inverters.

PRODUCT SUMMARY	
V_R	1200 V
V_F (typical)	2.8 V
t_{rr} (typical)	145 ns
$I_{F(DC)}$ at T_C per leg	60 A at 86 °C
$I_{F(AV)}$ at T_C per leg	60 A at 62 °C

ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage		V_R		1200	V
Continuous forward current	per leg	I_F	T_C = 86 °C	60	A
	per module			120	
Single pulse forward current		I_{FSM}	T_J = 25 °C	350	
Maximum repetitive forward current		I_{FRM}	Rated V_R, square wave, 20 kHz, T_C = 60 °C	130	
Maximum power dissipation		P_D	T_C = 25 °C	337	W
			T_C = 100 °C	135	
RMS isolation voltage		V_{ISOL}	Any terminal to case, t = 1 minute	2500	V
Operating junction and storage temperature range		T_J, T_{Stg}		- 55 to + 150	°C

ELECTRICAL SPECIFICATIONS (T_J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	I_R = 100 µA	1200	-	-	V
Forward voltage	V_{FM}	I_F = 60 A	-	2.8	4.0	
		I_F = 120 A	-	3.6	5.3	
		I_F = 60 A, T_J = 125 °C	-	2.7	-	
Reverse leakage current	I_{RM}	V_R = V_R rated	-	2.0	75	µA
		T_J = 150 °C, V_R = V_R rated	-	2.7	10	mA

DYNAMIC RECOVERY CHARACTERISTICS (T_J = 25 °C unless otherwise specified)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNITS**
Reverse recovery time	t_{rr}	T_J = 25 °C	I_F = 50 A dI_F/dt = - 200 A/µs V_R = 200 V	-	145	-	ns
		T_J = 125 °C		-	218	-	
Peak recovery current	I_{RRM}	T_J = 25 °C		-	13	-	A
		T_J = 125 °C		-	18	-	
Reverse recovery charge	Q_{rr}	T_J = 25 °C		-	910	-	nC
		T_J = 125 °C		-	1920	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNITS**
Junction to case, single leg conducting	R_{thJC}		-	-	0.37	°C/W
Junction to case, both legs conducting			-	-	0.185	
Case to heatsink	R_{thCS}	Flat, greased and surface	-	0.05	-	
Weight			-	30	-	g
Mounting torque			-	1.3	-	Nm

For technical questions within your region, please contact one of the following:
DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com

Document Number: 94608
Revision: 22-Jul-10

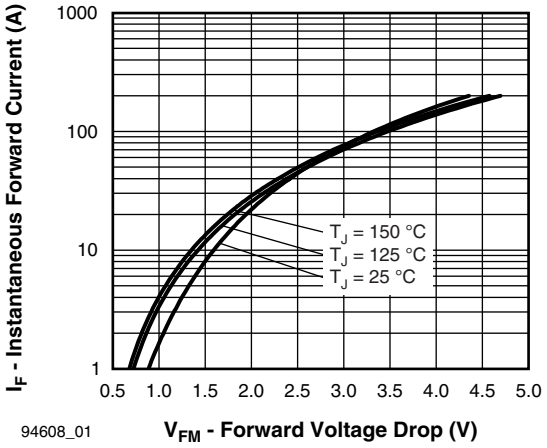

Fig. 1 - Typical Forward Voltage Drop Characteristics

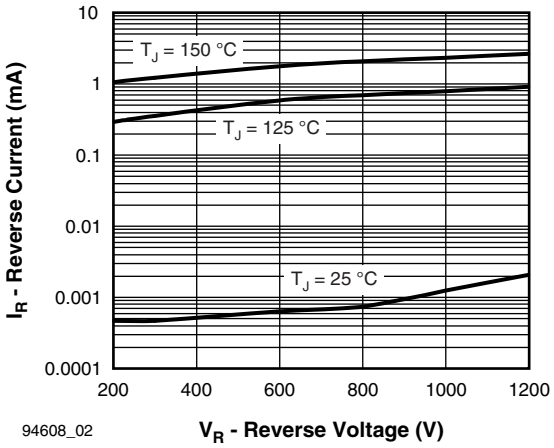

Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

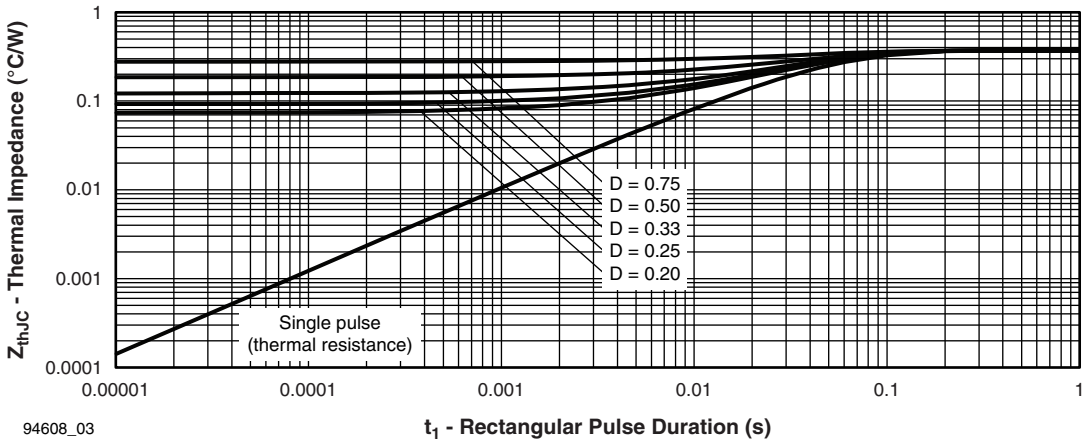

Fig. 3 - Maximum Thermal Impedance Z_{thJC} Characteristics

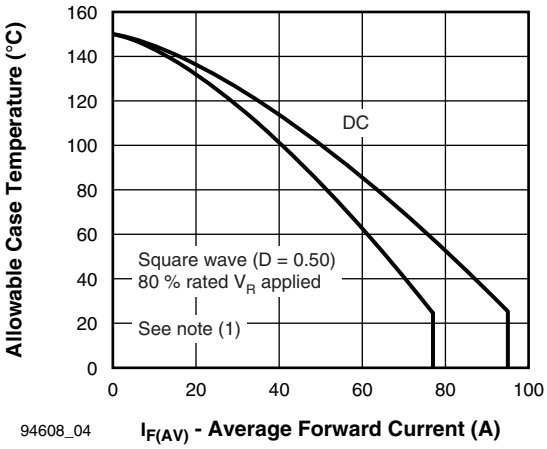

Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

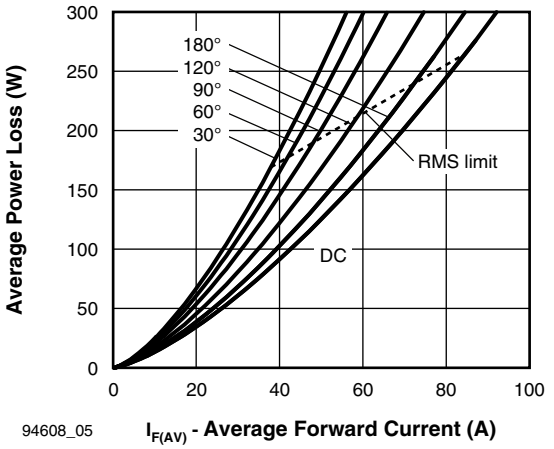

Fig. 5 - Forward Power Loss Characteristics

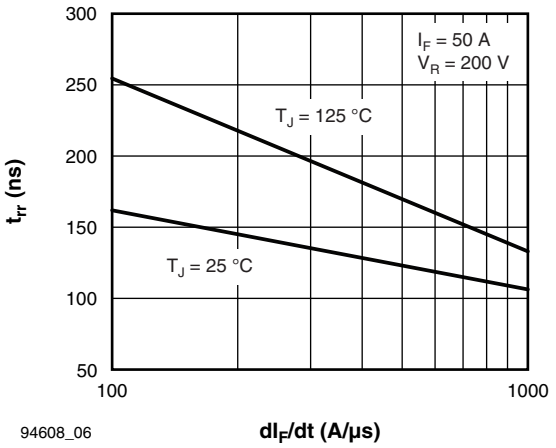

Fig. 6 - Typical Reverse Recovery Time vs. dI_F/dt

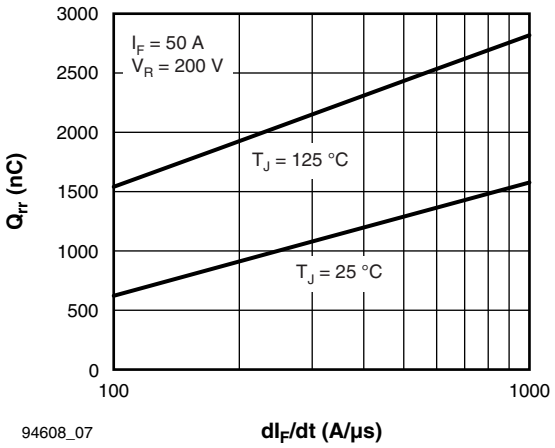

Fig. 7 - Typical Stored Charge vs. dI_F/dt

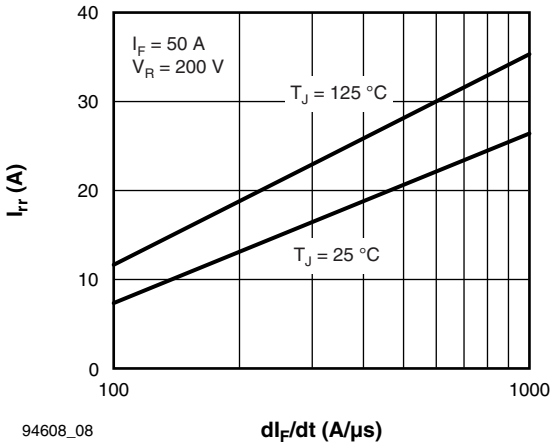

Fig. 8 - Typical Peak Recovery Current vs. dI_F/dt

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}$/D) (see fig. 5);
Pd_{REV} = Inverse power loss = $V_{R1} \times I_R$ (1 - D); I_R at V_{R1} = Rated V_R

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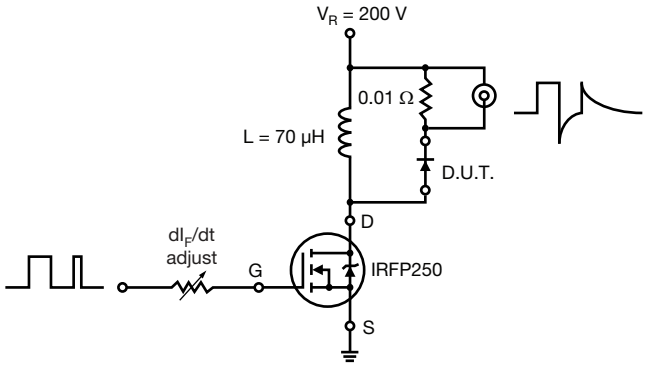
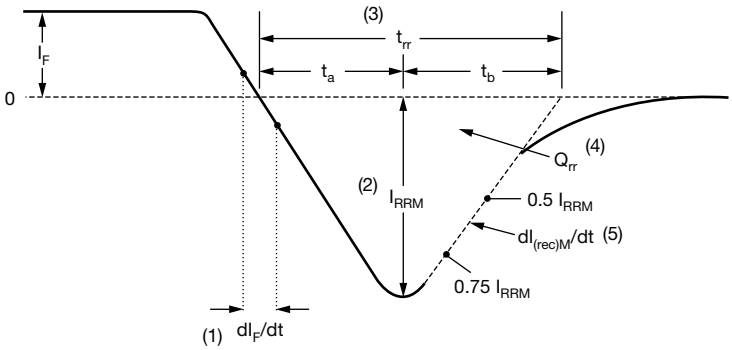


Fig. 9 - Reverse Recovery Parameter Test Circuit



(1) dI_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

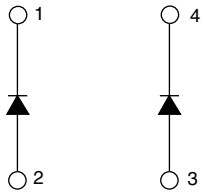
ORDERING INFORMATION TABLE

Device code

HF	A	120	FA	120	P
1	2	3	4	5	6

1 - HEXFRED® family
2 - Process designator (A = Electron irradiated)
3 - Average current (120 = 120 A)
4 - Package outline (FA = SOT-227)
5 - Voltage rating (120 = 1200 V)
6 - P = Lead (Pb)-free

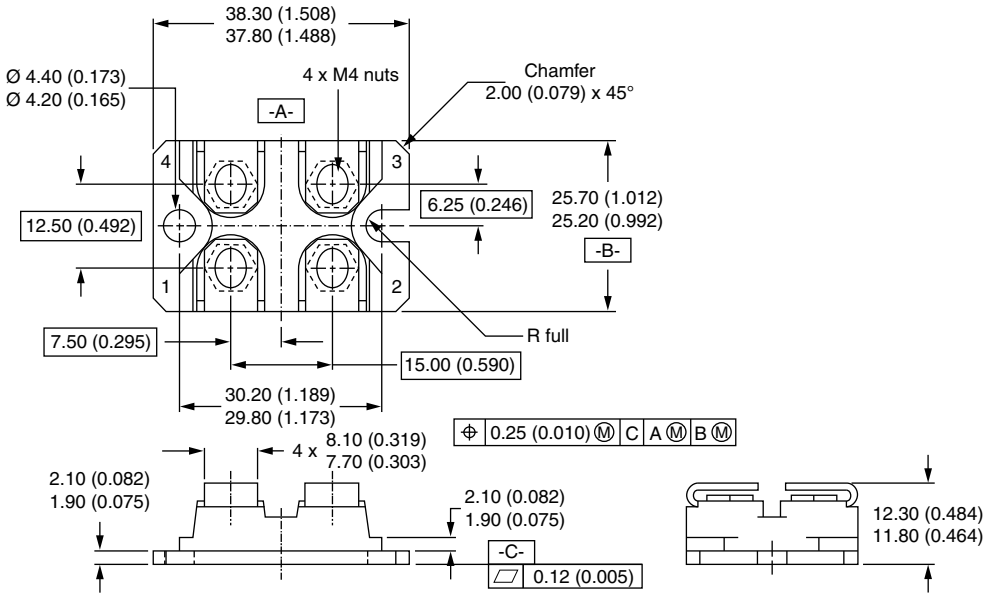
CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95036
Packaging information	www.vishay.com/doc?95037

SOT-227

DIMENSIONS in millimeters (inches)



Notes

- Dimensioning and tolerancing per ANSI Y14.5M-1982
- Controlling dimension: millimeter

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